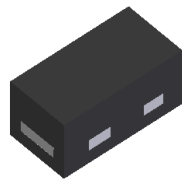


Features

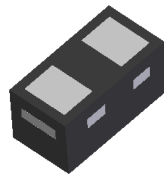
- Ultra-Small, Low Profile Leadless Surface Mount Package (0.6 x 0.3 x 0.3mm)
- Provides ESD Protection per IEC 61000-4-2 Standard: Air – ±30kV, Contact – ±30kV
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- Typically Used in Cellular Handsets, Portable Electronics, Communication Systems, Computers and Peripherals
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

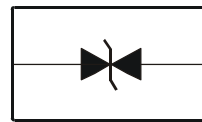
- Case: X3-DFN0603-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Weight: 0.0002 grams (Approximate)



Top View

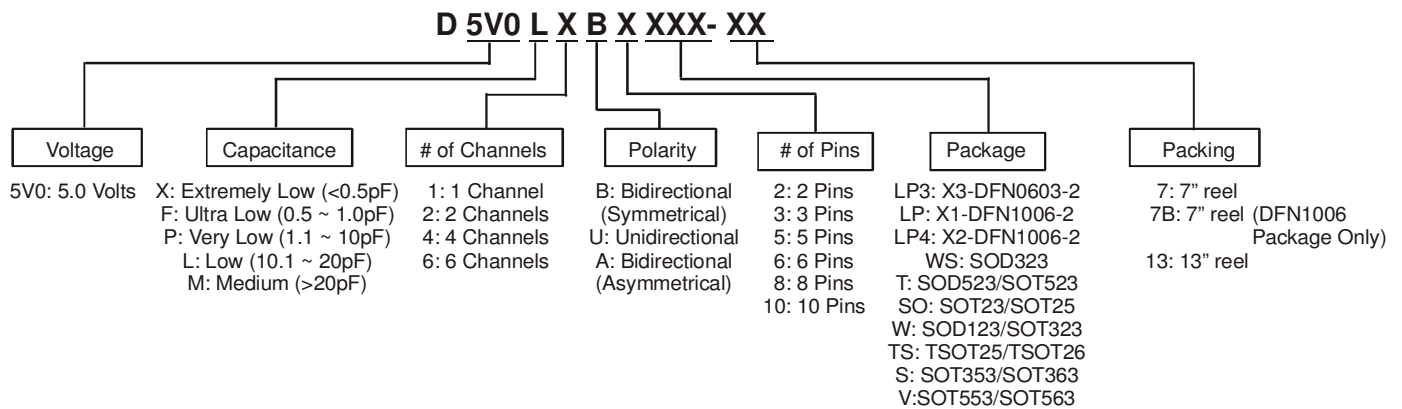


Bottom View



Device Schematic

Ordering Information (Note 4)

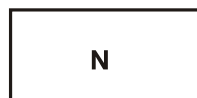


Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
D5V0L1B2LP3-7	Standard	N	7	8	10,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

X3-DFN0603-2



N = Product Type Marking Code

Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	84	W	8/20μs, Per Fig. 1
Peak Pulse Current	I _{PP}	6	A	8/20μs, Per Fig. 1
ESD Protection – Contact Discharge	V _{ESD_Contact}	±30	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V _{ESD_Air}	±30	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	—	—	5	V	—
Channel Leakage Current (Note 6)	I _{RM}	—	10	100	nA	V _{RWM} = 5V
Clamping Voltage, Positive Transients	V _{CL}	—	7.0	9.0	V	I _{PP} = 1A, t _p = 8/20μs, Figure 1
		—	8.7	10.7		I _{PP} = 3A, t _p = 8/20μs, Figure 1
		—	10.5	12.0		I _{PP} = 5A, t _p = 8/20μs, Figure 1
		—	11.5	14.0		I _{PP} = 6A, t _p = 8/20μs, Figure 1
Breakdown Voltage	V _{BR}	6	7	8	V	I _R = 1mA
Differential Resistance	R _{DIF}	—	0.2	—	Ω	I _R = 1A, t _p = 8/20μs
Channel Input Capacitance	C _T	—	15	18	pF	V _R = 0V, f = 1MHz
		—	12.5	—		V _R = 2.5V, f = 1MHz

- Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
6. Short duration pulse test used to minimize self-heating effect.

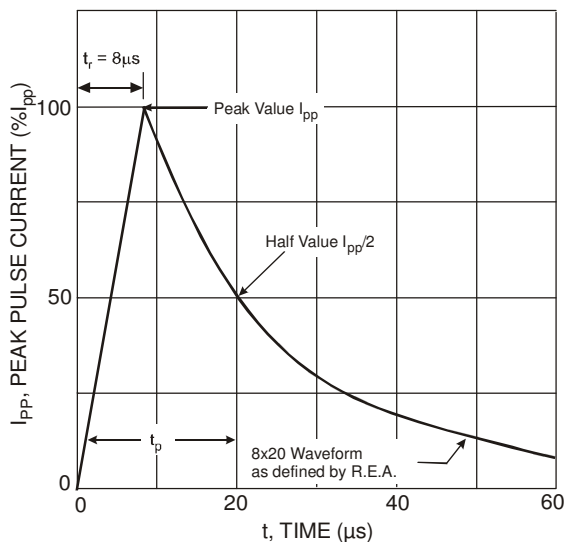


Figure 1 Pulse Waveform

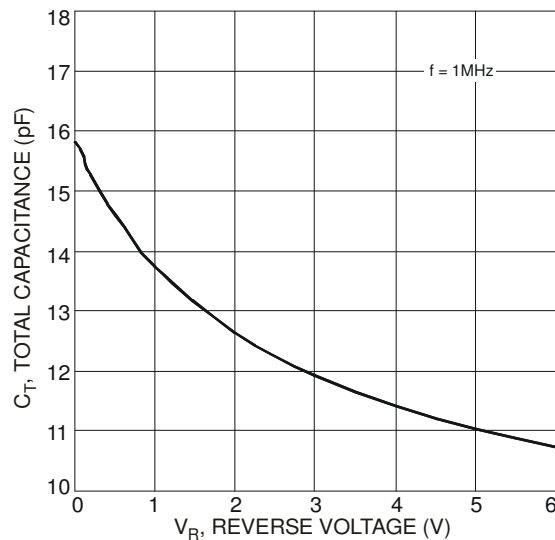


Figure 2 Typical Total Capacitance vs. Reverse Voltage

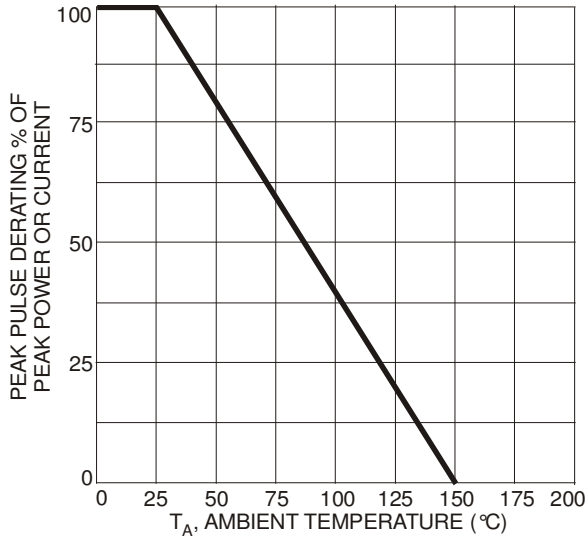


Figure 3 Pulse Derating Curve

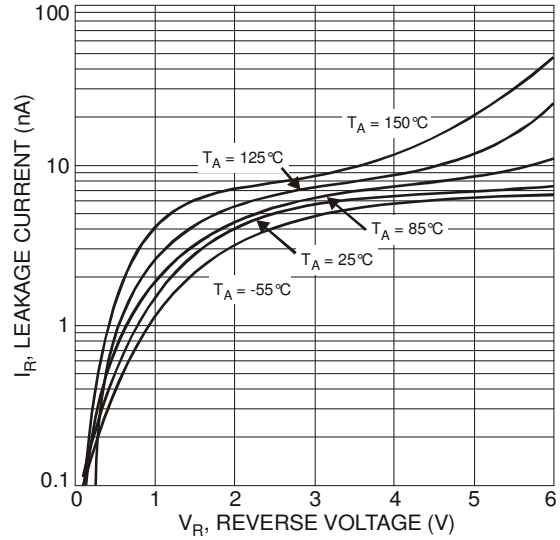


Figure 4 Typical Reverse Characteristics

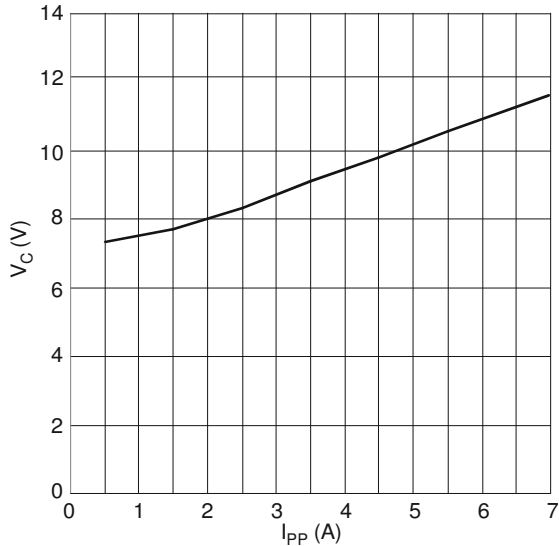


Figure 5 Typical Peak Clamping Voltage V_C vs. Peak Pulse Current I_{PP}

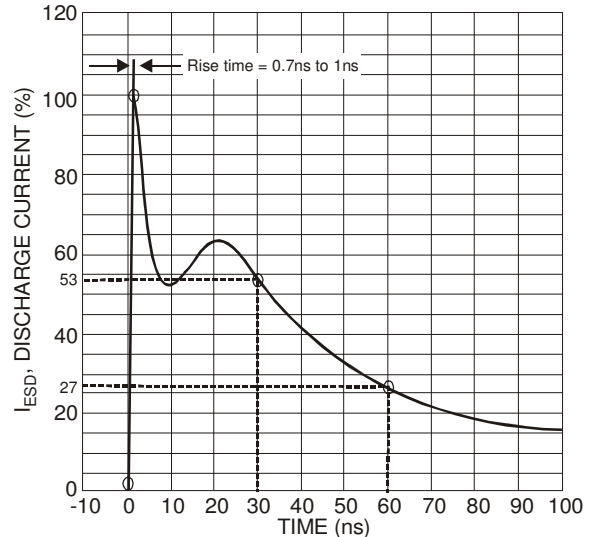


Figure 6 ESD Discharge Current Wave Form IEC 6100-4-2 (330Ω/150pF)

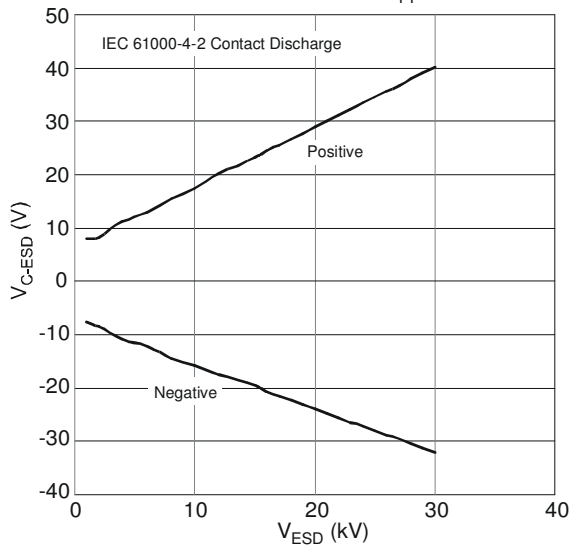


Figure 7 Typical Clamping Voltage vs. Contact Discharge Voltage

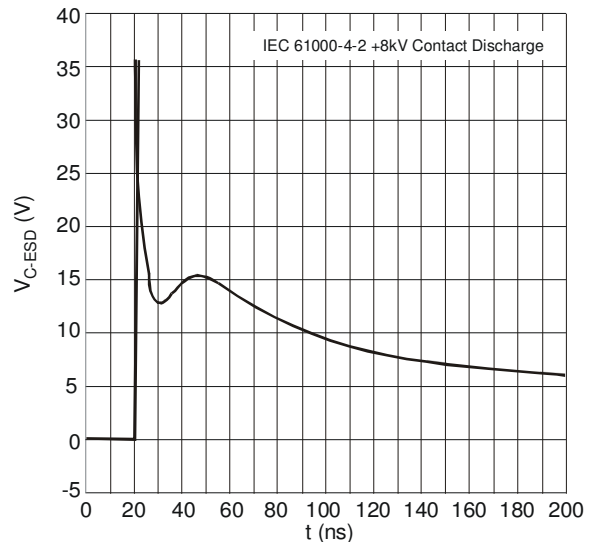


Figure 8 Typical Clamping Performance @ 8kV Contact Discharge

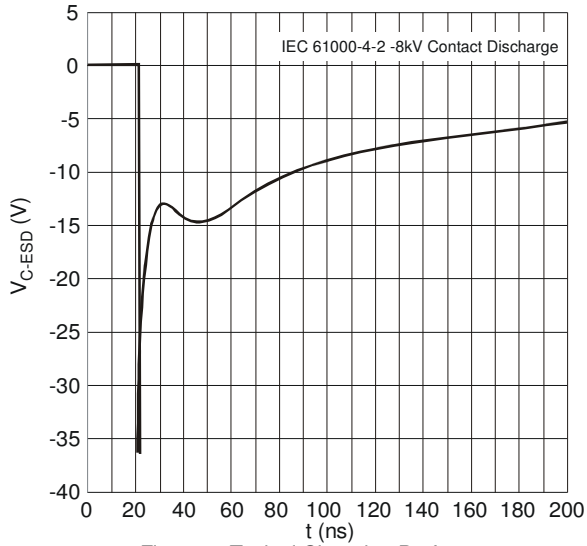
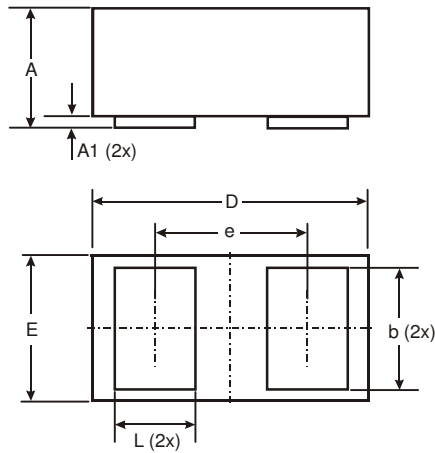


Figure 9 Typical Clamping Performance
@ -8kV Contact Discharge

Package Outline Dimensions

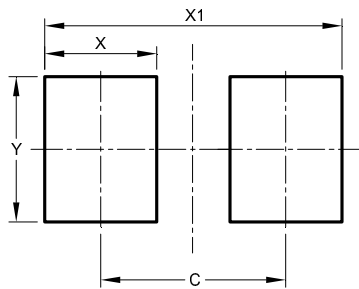
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X3-DFN0603-2			
Dim	Min	Max	Typ
A	0.27	0.35	0.30
A1	0.00	0.03	0.02
b	0.19	0.29	0.24
D	0.595	0.645	0.62
E	0.295	0.345	0.32
e	-	-	0.355
L	0.14	0.24	0.19
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.380
X	0.230
X1	0.610
Y	0.300

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